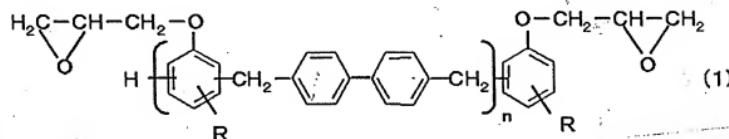


Amendments to the Specification

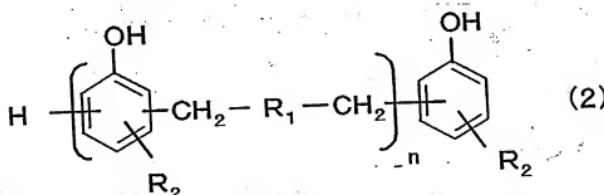
On page 3, replace lines 3-16 with the following:

This invention provides a resin composition for encapsulating a semiconductor chip

comprising: an epoxy resin (A) represented by general formula (1):



wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; a phenol resin (B) represented by general formula (2):

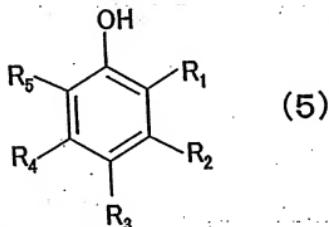


wherein R₁ represents phenylene or biphenylene; R₂ represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; an inorganic filler (C); a curing accelerator (D); a silane coupling agent (E); and Compound (F) containing two and more hydroxyl groups combined with each of on adjacent carbon atoms comprising an aromatic ring.

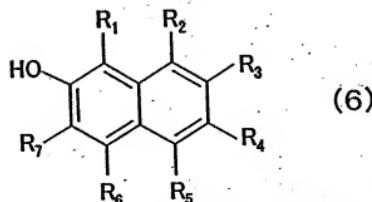
On page 13, please replace the paragraph beginning on line 4 to page 14, line 2, with the following:

Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring may contain optionally a substituent other than the hydroxyl groups.

Compound (F) may be a monocyclic compound represented by general formula (5):



wherein one of R₁ and R₅ is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than hydroxyl; and R₂, R₃ and R₄ are hydrogen, hydroxyl or a substituent other than hydroxyl; or a polycyclic compound represented by general formula (6):



wherein one of R₁ and R₇ is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than hydroxyl-hydroxyl; and R₂, R₃, R₄, R₅ and R₆ are hydrogen, hydroxyl or a substituent other than hydroxyl.

Please replace Table 1 on page 21 with the following table:

TABLE 1

	1	2	3	4	5	6	7	8	9	10	11	Examiner
Phenol bis(2-hydroxyethyl) type epoxy resin	7.25	4.0	6.65	7.75	7.13	7.42	7.25	7.25	7.35	7.35	7.35	
Bisphenol type epoxy resin	5.5	2.5	5.5	5.5	5.3	5.5	5.5	5.5	5.5	5.5	5.45	
Phenol bis(hydroxymethyl) resin	1.3											
Phenol-formaldehyde resin	8.0	8.0	8.45	8.0	8.0	8.10	8.0	8.0	8.0	8.0	8.0	
Sureflex flame retardant	0.4	0.5	0.3	0.05	0.05	0.03	0.03	0.04	0.04	0.04	0.04	
γ -Oxydicyclopentadiene/trimellitic anhydride												
7-Mercaptostituted trimellitic anhydride	0.2	0.13	0.25	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	
Thiophene/epoxyamine												
DBU												
Curing exo number of formula (7)												
Curing exo number of formula (8)												
2,2-Dimethoxyethane	0.05	0.07	0.1	0.25	0.02	0.35	0.05	0.05	0.05	0.05	0.05	
1,2-Dimethoxyethane												
Dioxane												
Propane												
β -Dichlorotoluene												
Resorcinol												
Carboxylic acid												
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	
Stirrer flow (cm ³)	100	85	121	115	95	118	104	105	102	112	105	
Stirrer flow (cc)	85	81	80	69	69	59	63	63	61	65	69	
Curing torque ratio												
Solder reworkability-testing	0	0	0	0	0	0	0	0	0	0	0	
Internal crack	0	0	0	0	0	0	0	0	0	0	0	
Fire retardancy	V-O											